

The 21th IEEE International Conference on Machine Learning and Applications (IEEE ICMLA-2022)

Special Session on: Machine Learning for Predictive Models in Engineering Applications (MLPMEA 2022)

December 12-15, 2022, The Bahamas, Caribbean

<https://www.icmla-conference.org/icmla22/>

Background and Aims

The MLPMEA 2022 special session provides an international forum for sharing knowledge and results on the theory, methodology, and applications of Machine Learning for developing predictive models for different engineering applications. Various Machine Learning methods can efficiently handle complex prediction problems and have abilities to handle large-scale datasets with uniform characteristics and noisy data. This MLPMEA 2022 special session covers topics related to building predictive models using different Machine Learning methods to solve specific problems that arise in the engineering domain. The MLPMEA encourages researchers to publicly share their data, to promote interdisciplinary research between the machine learning and engineering communities and conduct verifiable, repeatable experiments that practitioners can use.

Scope/Topics

Topics relevant to this session include, but are not limited to:

- Predictive modeling applications and pressing challenges/opportunities in engineering.
- Using predictive modeling for accelerating materials design.
- Developing predictive modeling tools that can assist engineers in defining, exploring, and evaluating alternative systems or designs.
- Using predictive modeling in additive manufacturing.
- Applications of artificial neural networks and other machine learning methods to solve engineering problems.

Submission Guidelines and Instructions

Papers submitted for review should conform to IEEE specifications. Manuscript templates can be downloaded from [IEEE website](#)¹. The maximum length of a paper is 8 pages. All the papers will go through a double-blind peer-review process. The authors' names and affiliations should not appear in the submitted paper. The authors' prior work should be cited in the third person. Authors should also avoid revealing their identities and institutions in the text, figures, links, etc.

Paper Publication:

Accepted papers will be published in the ICMLA 2022 conference proceedings (published by IEEE). A selected number of accepted papers will be invited for possible inclusion, in an expanded and revised form, in some journal special issues.

Important Dates:

- Submission Deadline: September 9, 2022
- Notification of Acceptance: October 7, 2022

¹ www.ieee.org/conferences_events/conferences/publishing/templates.html

- Camera-ready papers & Pre-Registration: October 14, 2022

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